Overview

HP 240 14-inch G9 Notebook PC



- 1. Internal Dual Digital Microphone
- 2. Webcam LED
- 3. Webcam
- 4. Touchpad
- 5. Touchpad Buttons
- 1. SuperSpeed USB 20Gbps is not available

Left

- 6. Power Indicator LED
- 7. Hard Drive Indicator LED
- SuperSpeed USB Type-C[®] 5Gbps signaling rate1 (Data Transfer Only)¹
- 9. Mini Security Lock Slot (Lock sold in select countries)
- 10. Power Button



Overview



- 1. Power Connector
- 2. RJ-45 / Ethernet Port
- 3. HDMI Port (Cable Sold Separately)
- 1. SuperSpeed USB 20Gbps is not available.

Right

- SuperSpeed USB Type-A 5Gbps signaling rate¹ port (USB 3.2 Gen 1)
- SuperSpeed USB Type-A 5Gbps signaling rate¹ port (USB 3.2 Gen 1)
- 6. Audio Combo Jack
- 7. Fingerprint Reader (Select Models)



Overview

AT A GLANCE

- Preinstalled with Windows 11 Pro, Windows Home or FreeDOS
- Choice of 12th generation Intel[®] Core[™], Intel[®] Pentium[®], or Intel[®] Celeron[®] processors
- NVIDIA® GeForce® MX550 (2 GB GDDR6 dedicated) (Optional)
- Choice of 35.56 cm (14") diagonal HD and UltraWide Viewing Angle FHD 400 nit display
- Optimize your video calls with an HD camera and temporal noise reduction that adjusts the lighting to your environment.
- Fast dual channel DDR4 SODIMM memory up to 32 GB
- Enhanced security features including discrete TPM 2.0 (select model) and optional Fingerprint reader
- Weight with basic configurations starting at 3.25 lb / 1.47 kg
- Support wireless options for connectivity on the go including gigabit-speed up to Wi-Fi[®] 6
- Supports fast charging (50% in 45 minutes) with no impact on battery recharge cycles
- MM18 Battery life up to 8 hours and 45 minutes
- Full size, optional backlit keyboard and clickpad with Precision Touchpad Supported certified
- Passed 13 MIL-STD test

NOTE: See important legal disclosures for all listed specs in their respective features sections.

PRODUCT NAME

HP 240 14-inch G9 Notebook PC

OPERATING SYSTEM

Preinstalled Windows 11 Pro¹

Windows 11 Pro Education¹ Windows 11 Home – HP recommends Windows 11 Pro for business¹ Windows 11 Home Single Language – HP recommends Windows 11 Pro for business^{1,2} Windows 11 Home Education – HP recommends Windows 11 Pro for business¹ FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

2. This computer is preinstalled with Windows 11 Home Single Language.

PROCESSORS

		L3		Max Fr		
Processor ^{3,4,5,6}	Cores	ores Threads	Cache	1-core and 2- core burst	3-core and 4- core burst	Base Frequency
Intel [®] Pentium [®] Silver N6000	4	4	4MB	3.3 GHz	3.1 GHz	1.1 GHz
Intel [®] Celeron [®] N5100	4	4	4MB	2.8 GHz	2.8 GHz	1.1 GHz
Intel [®] Celeron [®] N4500	2	2	4MB	2.8 GHz	NA	1.1 GHz

Processor ^{3,4,5,6}	Cores	Number	Number	Threads	L3	Max Turbo	Frequency	Base Fre	equency
		of P-cores	of E-cores	lineaus	Cache	P-cores	E-cores	P-cores	E-cores
Intel [®] Core™ i7-1255U	10	2	8	12	12MB	4.7 GHz	3.5 GHz	1.7 GHz	1.2 GHz
Intel [®] Core™ i7-1260P	12	4	8	16	18MB	4.7 GHz	3.4 GHz	2.1 GHz	1.5 GHz
Intel [®] Core™ i5-1240P	12	4	8	16	12MB	4.4 GHz	3.3 GHz	1.2 GHz	1.3 GHz
Intel® Core™ i5-1235U	10	2	8	12	12MB	4.4 GHz	3.3 GHz	1.3 GHz	0.9 GHz



Technical Specifications

Intel [®] Core™	6	2	4	8	10MB	4.4 GHz	3.3 GHz	1.2 GHz	0.9 GHz
i3-1215U									

3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

5. Intel[®] Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

CHIPSET

Chipset is integrated with processor.

GRAPHICS

Integrated

Intel[®] UHD Graphics Intel[®] Iris[®] X^e Graphics ⁷

Discrete

NVIDIA® GeForce® MX550 (2 GB DDR6 dedicated) 8

Supports

Support HD decode, DX12, HDMI 1.4b 9

7. Intel[®] Iris[®] X^e Graphics capabilities require system to be configured with Intel[®] Core[™] i5 or i7 processors and dual channel memory. Intel[®] Iris[®] X^e Graphics with Intel[®] Core[™] i5 or 7 processors and single channel memory will only function as UHD graphics.

8. Integrated graphics depends on processor. NVIDIA[®] Optimus[™] technology requires an Intel processor, plus an NVIDIA[®] GeForce[®] discrete graphics configuration and is available on Windows 10 Pro OS. With NVIDIA[®] Optimus[™] technology, full enablement of all discrete graphics video and display features may not be supported on all systems (e.g. OpenGL applications will run on the integrated GPU or the APU as the case may be).

9. HD content required to view HD images.



Technical Specifications

DISPLAY

Non-Touch

35.6 cm (14") diagonal FHD UWVA eDP + PSR anti-glare Low Blue Light, narrow bezel bent, 400 nits, 100% sRGB (1920 x 1080)^{9,10,11}

35.6 cm (14") diagonal FHD UWVA edp anti-glare, narrow bezel bent, 250 nits, 45% NTSC (1920x1080) ^{9,10,11} 35.6 cm (14") diagonal HD SVA eDP anti-glare, narrow bezel bent, 250 nits, 45% NTSC (1366 x 768) ^{9,10,11}

HDMI

Port supports resolutions up to 1920 x 1080 external resolution @60 Hz

Display Size 14" diagonal 35.56 cm (14") diagonal

9. HD content required to view HD images.10. Sold separately or as an optional feature.11. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

STORAGE AND DRIVES

Primary Storage

1 TB 5400 rpm SATA ¹² 500 GB 7200 rpm SATA ¹² 500 GB 5400 rpm SATA ¹²

Primary M.2 Storage

1 TB PCIe[®] NVMe[™] M.2 Value Solid State Drive ¹² 512 GB PCIe[®] NVMe[™] M.2 Value Solid State Drive ¹² 256 GB PCIe[®] NVMe[™] M.2 Value Solid State Drive ¹² 128 GB PCIe[®] NVMe[™] M.2 TLC Solid State Drive ¹²

Dual Storage (select models) ¹³

256 GB PCIe[®] NVMe[™] M.2 Value Solid State Drive + 1TB 5400rpm SATA 128 GB M.2 SATA-3 TLC Solid State Drive + 1TB 5400rpm SATA

12. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 11) is reserved for system recovery software.
13. JSL don't support dual storage due to design limitation.



MEMORY

Maximum Memory

32 GB DDR4-3200 SDRAM 14,15

Memory

8 GB DDR4-2933 SDRAM (1 x 8 GB) ^{14,15} 4 GB DDR4-2933 SDRAM ^{14,15} 32 GB DDR4-3200 SDRAM (2 x 16 GB) ^{14,15} 16 GB DDR4-3200 SDRAM (1 x 16 GB) ^{14,15} 16 GB DDR4-3200 SDRAM (2 x 8 GB) ^{14,15} 12 GB DDR4-3200 SDRAM (1 x 8 + 1 x 4GB) ^{14,15} 8 GB DDR4-3200 SDRAM (1 x 8 GB) ^{14,15} 8 GB DDR4-3200 SDRAM (2 x 4 GB) ^{14,15} 4 GB DDR4-3200 SDRAM (1 x 4 GB) ^{14,15}

Memory Slots

1SODIMM (Intel Pentium/Celeron speed runs up to 2933)^{14,15} Support Single Channel Memory 2 SODIMM (Intel 12th Generation Intel Core processor) (Core i 3/5/7 speed runs up to 3200)^{14,15} Both slots are customer non-accessible / non-upgradeable Supports Dual Channel Memory

14. All slots are non-accessible / non-upgradeable.

15. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN

Realtek RTL8822CE 802.11ac 2x2 Wi-Fi[®] + Bluetooth[®] 5 16 Realtek RTL8852BE 802.11ax 2x2 Wi-Fi[®] + Bluetooth[®] 5.2 17 Realtek RTL8821CE 802.11a/b/g/n/ac (1x1) Wi-Fi[®] with Bluetooth[®] 4.2 Combo 16

Miracast

Compatible with Miracast-certified devices (For Win11)¹⁸

Ethernet

Integrated 10/100/1000 GbE ¹⁹

16. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

17. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs.

18. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.

19. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.



AUDIO/MULTIMEDIA

Audio

2 Integrated stereo speakers Integrated Microphone

Speaker Power

2W/4ohm

Camera

720p HD camera with Temporal Noise Reduction 7,8

9. HD content required to view HD images. 10. Sold separately or as an optional feature.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

Full Size Textured island-style Keyboard and optional Backlit²⁰

Pointing Device Touchpad with multi-touch gesture support (PTP certified)

Function Keys

F1 - Open " How to get help in Windows 11" webpage

- F2 Brightness Down
- F3 Brightness Up
- F4 Display Switching
- F5 Blank
- F6 Mute
- F7 Volume Down
- F8 -Volume Up
- F9 Previous
- F10 Play/Pause

F11 - Next

F12 - Airplane mode

20. Backlit keyboard is an optional feature.



SOFTWARE AND SECURITY

Software

MYOffice MyHP HP QuickDrop²¹ HP Privacy Settings HP SUPPORT ASSISTANT ²² HP Audio Switch HP Connection Optimizer HP PC Hardware Diagnostics HP Smart Health HP Smart²³

Manageability Features

Touchpoint Customizer for Consumer

NOTE: To enhance brightness, level go to the Intel[®] Graphics Command Center app, click on System and turn off the Display Power Savings function.

Security Management

McAfee Security (30 days free trial as default) ²⁴ Express VPN (30 days free trial) LastPass password manager Discrete TPM 2.0 (select model) / Firmware TPM 2.0 ²⁵ Fingerprint Reader ²⁶

21. HP Quick Drop requires Internet access and Windows 10 and higher PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app

22. HP Support Assistant requires Windows and Internet access.

23. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or it can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support

24. 30-day McAfee[®] LiveSafe[™] trial included. Internet access required and not included. Subscription required after expiration. See http://www.McAfee.com for more details.

25. Firmware TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).

26. HP Fingerprint sensor is an optional feature that must be configured at purchase.



Technical Specifications

POWER

Power Supply

HP Smart 65 W External AC power adapter ²⁷ HP Smart 65 W EM External AC power adapter ²⁷ HP Smart 45 W External AC power adapter ²⁷

Battery

HP Long Life 3-cell, 41 Wh Li-ion Polymer ^{28,29} Compliant with UL 1642 Standard

Power Cord 1M (3.28 feet) length power cord

Battery Life Up to 8 hours 45 minutes ³⁰

Battery Weight

0.39 lb 0.18 kg

27. Availability may vary by country.

28. Battery is internal and not replaceable by customer. Serviceable by warranty.

29. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

30. Windows MM18 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.



WEIGHTS & DIMENSIONS

Product Weight

Starting at 3.25 lb ³¹ Starting at 1.47 kg ³¹

Product Dimensions (W x D x H)

12.76 x 8.89 x 0.78 in 32.4 x 22.59 x 1.99 cm

31. Weight will vary by configuration. Does not include power adapter.

PORTS/SLOTS

Ports

2 SuperSpeed USB Type-A 5Gbps signaling rate (USB 3.2 Gen 1)
1 SuperSpeed USB Type-C[®] 5Gbps signaling rate (Data Transfer Only)
1 HDMI v1.4b ³²
1 RJ-45
1 AC Power
1 Headphone/microphone combo jack

32. HDMI cable sold separately.



SERVICE AND SUPPORT

HP Services offers 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.³³

33. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



SYSTEM UNIT

Stand-Alone Power Requirements	
(AC Power) Nominal Operating Voltage	19.5 V
Average Operating Power	5.56W
Integrated graphics	Yes
Discrete Graphics	N/A (Switchable graphics design)
	N/A (Switchable graphics design)
Max Operating Power	Discrete < 65W UMA < 45W
Temperature	
Operating	32° to 95° F (0° to 35° C) (not writing optical) 41° to 95° F (5° to 35° C) (writing optical)
Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	
Operating	10% to 90%, non-condensing
Non-operating	5% to 95%
Shock	
Operating	40 G, 2 ms duration, half-sine
Non-operating	240 G, 2 ms duration, half-sine
Random Vibration	
Operating	1.043 grams
Non-operating	3.5 grams
Altitude (unpressurized)	
Operating	-15 m to 3048 m (-50 ft to 10000 ft)
Non-operating	-15 m to 12192 m (-50 ft to 40000 ft)
Planned Industry Standard Certifications	
Regulatory Model Number	TPN-I130
UL	Yes
CSA	Νο
FCC Compliance	Yes
	Yes ³⁴
EPEAT [®]	Yes, EPEAT [®] registered ³⁵
ICES	Yes
Australia /	Yes
NZ A-Tick Compliance	Yes
CCC	Yes
Japan VCCI Compliance	Yes
кс	Yes
BSMI	Yes
CE Marking Compliance	Yes
CU/EAC	Yes
CIT	N/A
Saudi Arabian Compliance (ICCP)	Yes
SABS	Yes
UKRSERTCOMPUTER	Yes



Technical Specifications

34. Configurations of the HP 240 14-inch G9 Notebook PC that are ENERGY STAR[®] qualified are identified as HP 240 14-inch G9 Notebook PC ENERGY STAR on HP websites and on http://www.energystar.gov.
35. Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. EPEAT[®] status varies by country. Visit http://www.epeat.net for more information.

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

1. Actual brightness will be lower with touchscreen or HP Sure View.

Panel LCD 14-in FHD	Outline Dimensions (W x H)	316.170 x 197.980 max.
(1920x1080) Anti-Glare WLED UWVA 45percent cg 250nits eDP NWBZ slim	Active Area	309.37 x 174.02
	Weight	<285g max.
	Diagonal Size	14.0"
	Thickness	3.0mm max.
	Interface	eDP 1.2
	Surface Treatment	Anti-glare (AG) No 600:1 (typ) 60Hz
	Touch Enabled	
	Contrast Ratio	
	Refresh Rate	
	Brightness	250nit typ.
	Pixel Resolution	1920 x 1080 (FHD)
	Format	WLED
	Backlight	RGB
	Color Gamut Coverage Color Depth	NTSC 45%
		6bits
	Viewing Angle	UWVA 85/85/85/85
	Low Blue Light	NO
	Power Consumption (W, EBL@ 150nits max/ 200nits max)	<2.52W max./ No define
Panel LCD 14-in HD (1366x768)	Outline Dimensions (W x H)	316.200x198.040max. (w/PCB)
Anti-Glare WLED SVA 45percent	Active Area	309.4 x 173.95
cg 250nits eDP NWBZ ultraslim	Weight	285g Max
	Diagonal Size	14"
	Biagonal Jize	2.0

LED SVA 45percent	Active Area	309.4 x 173.95	
DP NWBZ ultraslim	Weight	285g Max	
	Diagonal Size	14"	
	Thickness	3.0mm max.	
	Interface	eDP 1.2	
	Surface Treatment	Anti-Glare	
	Touch Enabled	No	
	Contrast Ratio	300:1 (typ)	
	Refresh Rate	60Hz	
	Brightness	250nits	
	Pixel Resolution	1366 x 768 (HD)	
	Format	WLED	

	Backlight Color Gamut Coverage Color Depth Viewing Angle Low Blue Light Power Consumption (W, EBL@ 150nits max/200nits max)	RGB NTSC 45% 6bits 45/45/15/30 No <2.52W max./ <2.86W max.
14.0 in FHD (1920 x 1080) Anti- Glare UWVA Low Blue Light sRGB NWBZ 400 eDP 1.4+PSR2 100 flat LCD Panel	Outline Dimensions (W x H) Active Area Weight	316.170 x 196.880 (max) (w/PCB) 309.370 x 174.020 mm (typ.) 295 g (max)
	Diagonal Size Thickness Interface	14.0 (inch) 3.0 mm (max) eDP 1.4 (2 lane) Anti-Glare
	Surface Treatment Touch Enabled Contrast Ratio	No 1000:1 (typical)
	Refresh Rate Brightness Pixel Resolution	60Hz 400 nits 1920 x 1080 (FHD)
	Format Backlight Color Gamut Coverage	WLED RGB sRGB 100%
	Color Depth Viewing Angle Low Blue Light	[bits/color] 8 UWVA 89/89/89 Yes
	Power Consumption (W, EBL@ 150nits max/ 200nits max)	2.1 (max)/ 2.7 (max)



STORAGE AND DRIVES

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 11) is reserved for system recovery software.

for system recovery software.				
HDD 1TB 5400RPM 7mm SATA	Drive Weight	0.21 lbs (95 g)		
	Rotation speed	5400rpm		
	NAND Type	up to 128MB		
	Height	0.28 in (7 mm)		
	Width	2.75 in (69.85 mm)		
	Weight	ATA-8, SATA 3.0		
	Interface	600MB/s (Interface)		
	Maximum Sequential Read	Single Track: 1.5ms		
		Agerage: 13ms		
	Maximum Convertial Maite	Maximum: 32ms		
	Maximum Sequential Write Logical Blocks	1,953,525,168 0° to 60°C [case temp]		
	Operating Temperature	ATA Security		
	Features	•		
		S.M.A.R.T., NCQ, Ultra DMA		
HDD 500GB 5400RPM 7mm	Drive Weight	0.21 lbs (95 g)		
SATA	Rotation speed	5400rpm up to 128MB		
	Cache Buffer			
	NAND Type/Size	N/A		
	Height	0.28 in (7 mm) 2.75 in (69.85 mm)		
	Width			
	Interface	ATA-8, SATA 3.0		
	Transfer Rate	600MB/s (Interface)		
	Seek Time	Single Track: 1.5ms		
		Agerage: 13ms		
		Maximum: 32ms		
	Logical Blocks	976,773,168		
	Operating Temperature	0° to 60°C [case temp]		
	Security Features	ATA Security		
	Features	S.M.A.R.T., NCQ, Ultra DMA		
HDD 500GB 7200RPM 7mm	Drive Weight	0.21 lbs (95 g)		
SATA	Rotation speed	7200rpm		
	Cache Buffer	up to 128MB		
	Height	0.28 in (7 mm)		
	Width	2.75 in (69.85 mm)		
	Interface	ATA-8, SATA 3.0		
	Transfer Rate	600MB/s (Interface)		
	Seek Time	Single Track: 1.5ms		
		Agerage: 13ms		
		Maximum: 32ms		



l'echnical Specifica		
	Logical Blocks	976,773,168
	Operating Temperature	0° to 60°C [case temp]
	Security Features	ATA Security
	Features	S.M.A.R.T., NCQ, Ultra DMA
64GB eMMC 5.x	Form Factor	eMMC
	Capacity	64GB
	NAND Type	MLC/TLC
	Height	1.4mm
	Width	11.5x13mm
	Weight	0.2g
	Interface	MMC protocal
	Maximum Sequential Read	Update to 250MB/s
	Maximum Sequential Write	Update to 70MB/s
	Logical Blocks	64GB(62,537,072,640 Bytes)
	Operating Temperature	0 to 70
	Features	HS400
SSD 128GB 2280 PCIe-3x2	Form Factor	M.2 2280
Three Layer Cell	Capacity	128GB
•	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	up to 1600MB/s ±20%
	Maximum Sequential Write	•
	Logical Blocks	up to 900MB/s ±20% 250,069,680
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	Pyrite
SSD 1TB 2280 PCIe NVMe	Form Factor	M.2 2280
Value		M.2 2280 1TB
	Capacity NAND Type	Value
	Height Width	0.09 in (2.3 mm) 0.87 in (22 mm)
	Width	
	Interface Maximum Convential Board	PCIe NVMe
	Maximum Sequential Read	up to 2300MB/s ±20%
	Maximum Sequential Write	up to 2000MB/s ±20%
	Logical Blocks Operating Temperature	2,000,409,264 32° to 158°F (0° to 70°C) [ambient temp]
	Features	Pyrite
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SSD 256GB 2280 PCIe NVMe Value	Form Factor	M.2 2280			
	Capacity	256GB			
	NAND Type	Value			
	Height	0.09 in (2.3 mm)			
	Width	0.87 in (22 mm)			
	Weight	0.02 lb (10 g) PCIe NVMe up to 2300MB/s ±20% up to 1280MB/s ±20%			
	Interface				
	Maximum Sequential Read				
	Maximum Sequential Write				
	Logical Blocks	500,118,192 32° to 158°F (0° to 70°C) [ambient temp]			
	Operating Temperature				
	Features	Pyrite			
SSD 512GB 2280 PCIe	Form Factor	M.2 2280			
NVMe Value	Capacity	512GB			
	NAND Type	Value			
	Height	0.09 in (2.3 mm)			
	Width	0.87 in (22 mm)			
	Interface	PCIe NVMe			
	Maximum Sequential Read	up to 2300MB/s ±20%			
	Maximum Sequential Write	up to 1400MB/s ±20%			
	Logical Blocks	1,000,215,216			
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]			
	Features	Pyrite			



NETWORKING/COMMUNICATIONS

Realtek 802.11a/b/g/n/ac (1x1) Wi-Fi® and Bluetooth® 4.2 Combo ¹		IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11k IEEE 802.11k IEEE 802.11v
	Interoperability Frequency Band	Wi-Fi certified modules •802.11b/g/n 2.402 – 2.482 GHz •802.11a/n/ac 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 150Mbps 802.11ac : max 433.3Mbps
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security ³	 IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification IEEE 802.11i WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power ²	 802.11b : +14dBm minimum 802.11g : +12dBm minimum 802.11a : +12dBm minimum 802.11n HT20(2.4GHz) : +12dBm minimum 802.11n HT40(2.4GHz) : +12dBm minimum 802.11n HT20(5GHz) : +10dBm minimum 802.11n HT40(5GHz) : +10dBm minimum 802.11ac VHT80(5GHz) : +10dBm minimum
	Power Consumption	 Transmit mode 2.0 W Receive mode 1.6 W Idle mode (PSP) 180 mW (WLAN Associated)



		 Idle mode 50 m¹ Connected Stan Radio disabled 8 	2			
Power Mana	gement	ACPI and PCI Express compliant power management 802.11 compliant power saving mode				
Receiver Ser	sitivity ⁴	802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0 : -84dBm maximum 802.11ac, MCS9 : -59dBm maximum				
Antenna typ	e	High efficiency antenna. One embedded dual band 2.4/5 GHz antenna is provided to the card to support WLAN communications and Bluetooth communications				
Form Factor		PCI-Express M.2 MiniCard				
Dimensions		Type 2230 : 2.3 x 22.0 x 30.0 mm				
Weight		Type 2230 : 2.8g				
Operating Vo	oltage	3.3v +/- 9%				
Temperature	2	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)			
Humidity		Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)"			
Altitude		Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)			
LED Activity		LED Amber – Radio OFF; LED OFF – Radio ON				
ith Bluetooth 4	.0/4.1/4.2 Wir	eless Technology				
Bluetooth Sp	pecification	4.0/4.1/4.2 Compliant				

HP Integrated Module wi

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Bluetooth Specification	4.0/4.1/4.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.

1. Wi-Fi 5 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. 1. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



Realtek RTL8852BE 802.11ax 2x2 Wi-Fi® + Bluetooth® 5.2 (802.11ax 2x2, supporting gigabit data rate) ¹	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi certified modules
	Frequency Band	•802.11b/g/n/ax 2.402 – 2.482 GHz •802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	•802.11b: 1, 2, 5.5, 11 Mbps •802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: max 300Mbps •802.11ac: max 866.7Mbps • 802.11ax: max 1201Mbps
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security ³	 IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification IEEE 802.11i WAPI
	Network Architecture	Ad-hoc (Peer to Peer)
	Models	Infrastructure (Access Point Required)
	Roaming Output Power ²	IEEE 802.11 compliant roaming between access points • 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ax HE40(2.4GHz): +10dBm minimum • 802.11ax HE80(5GHz): +10dBm minimum
	Power Consumption	•Transmit mode:2.5 W



Technical Specifications

	•Idle mode:50 m	180 mW(WLAN Associated) W(WLAN unassociated) dby/Modern Standby: 10mW		
Power Management		ACPI and PCI Express compliant power management 802.11 compliant power saving mode		
Receiver Sensitivity⁴	 •802.11b, 1Mbps : -93.5dBm maximum •802.11b, 11Mbps : -84dBm maximum •802.11a/g, 6Mbps : -86dBm maximum •802.11a/g, 54Mbps : -72dBm maximum •802.11n, MCS07 : -67dBm maximum •802.11n, MCS15 : -64dBm maximum •802.11ac, MCS0 : -84dBm maximum •802.11ac, MCS9 : -59dBm maximum •802.11ax, MCS11(HE40): -57dBm maximum •802.11ax, MCS11(HE80): -54dBm maximum 			
Antenna type	enclosure Two embedded o	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications		
Form Factor	PCI-Express M.2	MiniCard		
Dimensions		1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm		
Weight	1. Type 2230: 2.8 2. Type 126: 1.3			
Operating Voltage	3.3v +/- 9%			
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)		
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)		
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)		
LED Activity	LED Amber – Rac LED Off – Radio (
with Bluetooth 4.0/4.1/4.2/5	5.0/5.1/5.2 Wireles	s Technology		
Plustaath Specification	4 0/4 1/4 2/5 0/	E 1/E 2 Compliant		

HP Integrated Module w

Bluetooth Specification	4.0/4.1/4.2/5.0/5.1/5.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.

1. Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with



prior 802.11 specs.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Realtek RTL8822CE 802.11ac 2x2 Wi-Fi® + Bluetooth® ¹	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11k IEEE 802.11k IEEE 802.11v
	Interoperability Frequency Band	Wi-Fi certified modules •802.11b/g/n 2.402 – 2.482 GHz •802.11a/n/ac 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 300Mbps 802.11ac : max 866.7Mbps
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security ³	 IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification IEEE 802.11i WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power ²	 802.11b : +18.5dBm minimum 802.11g : +17.5dBm minimum 802.11a : +18.5dBm minimum 802.11n HT20(2.4GHz) : +15.5dBm minimum 802.11n HT40(2.4GHz) : +14.5dBm minimum 802.11n HT20(5GHz) : +15.5dBm minimum



			GHz) : +14.5dBm minimum (5GHz) : +11.5dBm minimum	
Power Consu	•	smit mode :2		
		ive mode :1. mode (PSP) 1	6 w 180 mW (WLAN Associated)	
			N (WLAN unassociated)	
		iected Stand o disabled: 8	lby/Modern Standby: 10mW RmW	
Power Manag			ess compliant power management	
			power saving mode	
Receiver Sens	-		-93.5dBm maximum	
			: -84dBm maximum : -86dBm maximum	
	802.11	1a/g, 54Mbp	s : -72dBm maximum	
			-67dBm maximum -64dBm maximum	
			-84dBm maximum	
			59dBm maximum	
Antenna type	e High el enclos		tenna with spatial diversity, mounted in the display	
			al band 2.4/5 GHz antennas are provided to the card t	0
			10 communications and Bluetooth communications	
Form Factor		press M.2 M		
Dimensions	• •		x 22.0 x 30.0 mm ′ x 12.0 x 16.0 mm	
Weight	• •	e 2230 : 2.8 <u>0</u> e 126: 1.3g	g	
Operating Vo	ltage 3.3v +/	/- 9%		
Temperature		-	14° to 158° F (–10° to 70° C)	
Humidity	Non-o Operat		–40° to 176° F (–40° to 80° C) 10% to 90% (non-condensing)	
numuty		-	5% to 95% (non-condensing)	
Altitude	Operat	-	0 to 10,000 ft (3,048 m)	
			0 to 50,000 ft (15,240 m)	
LED Activity		mber – Radio ff – Radio ON		
HP Integrated Module with Bluetooth 4.	0/4.1/4.2/5.0 Wirele	.0 Wireless Technology		
Bluetooth Sp		4.0/4.1/4.2/5.0 Compliant		
Frequency Ba		2402 to 2480 MHz		
Number of Av Channels	BLE : 0	y : 0~79 (1 M)~39 (2 MHz/	/СН)	
Data Rates ar Throughput			ata rate; throughput up to 2.17 Mbps rate; throughput up to 0.2 Mbps	
Throughput			ous Connection Oriented links up to 3, 64 kbps, voice	
	channe	els		
			nous Connection Less links 2178.1 kbps/177.1 kbps 5) or 864 kbps symmetric (3-EV5)	
Transmit Pow	-		nponent shall operate as a Class II Bluetooth device wi	ith
	a maxi	imum transn	nit power of + 4 dBm for BR and EDR.	

1. Wi-Fi 5 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels. Wireless access point and internet service



Technical Specifications

required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Realtek RTK8111HSH 10/100/1000 Integrated NIC	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21- 30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	Performance Features	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K
	Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) (MSC is supported on selected model) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status



POWER

1. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

HP 65W Smart AC	Dimensions (H x W x D)	D) 90x51x28.5mm		
adapter	Weight Input	230g +/- 10g (Not including power cord. Power cord varies by country.) 100 to 240 VAC		
	• • •	Input Efficiency	88.0 % at 115 VAC and 89.0 % at 230VAC	
		Input frequency range	48 ~ 63 Hz	
		Input AC current	Max. 1.7 A at 90 VAC	
	Output	Output power	65W	
		DC output	19.5V	
		Hold-up time	5ms at 115 Vac input	
		Output current limit	<11.0A Over voltage protection- 29V max automatic shutdown	
	Connector	4.5mm Barrel Type, 3 pin/g	rounded, mates with interchangeable cords	
	Environmental Design	Operating temperature Non-operating (storage) temperature	32°F to 95°F (0° to 35°C) -4°F to 185°F (-20° to 85°C)	
		Altitude	1 to 16,400 ft (0 to 5,000m)	
		Humidity	20% to 95%	
		Storage Humidity	10% to 95%	
	Certifications	* Worldwide safety standar EN60950-1 and/or EN6236 SELV; Agency approvals - C-UL-U Class B, CISPR32 Class B, CO	with LVD and EMC directives ds - IEC60950-1 and/or IEC62368-1, 8-1, UL60950-1 and/or UL62368-1 , Class1, S, NORDICS, DENAN, EN55032 Class B, FCC CC, NOM-001 NYCE. rs at 25°C ambient condition.	
HP 45W Smart AC	Dimensions	95x40x26.5mm		
adapter	Weight Input	200g +/- 10g (Not including power cord. Power cord varies by 100 to 240 VAC		
		Input Efficiency	88.0 % at 115 VAC and 89.0 % at 230VAC	
		Input frequency range	48 ~ 63 Hz	
		Input AC current	Max. 1.4 A at 90 VA	
	Output	Output power	45W	
		DC output	19.5V	
		Hold-up time	5ms at 115 Vac input	
	Connector	Output current limit 4.5mm Barrel Type, 3 pin/g	<8.0A Over voltage protection- 29V max automatic shutdown prounded, mates with interchangeable cords	
	Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)	
		Non-operating (storage) temperature	-4°F to 185°F (-20°to 85°C)	

Technical Specifications				
		Altitude Humidity	1 to 16,400 ft (0 to 5,000m) 20% to 95%	
		Storage Humidity	10% to 95%	
	EMI and Cafaty		10% 10 55%	
	EMI and Safety Certifications	* Worldwide safety sta EN60950-1 and/or EN SELV; Agency approvals - C- Class B, CISPR32 Class	ance with LVD and EMC directives andards - IEC60950-1 and/or IEC62368-1, 62368-1, UL60950-1 and/or UL62368-1 , Class1, UL-US, NORDICS, DENAN, EN55032 Class B, FCC 5 B, CCC, NOM-001 NYCE.) hours at 25°C ambient condition.	
HP 65W EM Smart AC	Dimensions	102vEEv20mm		
adapter		102x55x30mm 250g +/- 10g (Not including power cord. Power cord varies by country.)		
•	Weight Input	100 to 240 VAC	duling power cord. Power cord varies by country.)	
	mput	Input Efficiency Input frequency	88.0 % at 115 VAC and 89.0 % at 230VAC 48 ~ 63 Hz	
		range Input AC current	Max. 1.7 A at 90 VAC	
	Output	Output power	65W	
		DC output	19.5V	
		Hold-up time	5ms at 115 Vac input	
		Output current limit	<11.0A Over voltage protection- 29V max automatic shutdown	
	Connector	4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable		
	Environmental Design	Operating temperature	32ºFto 95ºF (0ºto 35ºC)	
		Non-operating (storage) temperature	-4ºFto 185ºF (-20ºto 85ºC)	
		Altitude	1 to 16,400 ft (0 to 5,000m)	
		Humidity	20% to 95	
	EMI and Safety Certifications	* Worldwide safety sta EN60950-1 and/or EN SELV; Agency approvals - C- Class B, CISPR32 Class	10% to 95% ance with LVD and EMC directives andards - IEC60950-1 and/or IEC62368-1, 62368-1, UL60950-1 and/or UL62368-1 , Class1, UL-US, NORDICS, DENAN, EN55032 Class B, FCC 5 B, CCC, NOM-001 NYCE. 0 hours at 25°C ambient condition.	

Dimensions (H x W x L) Weight	6.0 x 186.85 x 90.2 mm (0.23 x 7.29 x 3.52 inch) 0.175 Kg (0.385 lb)
Cells/Type	3cell lithium-Ion Polymer cell 515974
Energy	
Voltage	11.34V/11.28V
Amp-hour capacity	3.62Ah/3.635Ah
Watt-hour capacity	41Wh
Temperature	
Operating (Charging)	32° to 113° F (0° to 45° C)
Operating (Discharging)	14° to 122° F (-10° to 60° C)
Fuel Gauge LED	N/A
Warranty	1-year
Optional Travel Battery Available	No
	Weight Cells/Type Energy Voltage Amp-hour capacity Watt-hour capacity Temperature Operating (Charging) Operating (Discharging) Fuel Gauge LED Warranty Optional Travel



Technical Specifications

AUDIO

HD Stereo Codec	Realtek ALC3247
Audio I/O Ports	One Headset Combo-Jack connector support CTIA spec.
Internal Speaker Amplifier	2W class D stereo amplifier for the internal speaker only. External speakers must be powered.
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the Combo jack or integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 48 kHz for DAC and ADC.
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes.
# of Channels on Line-Out	0
Internal Speaker	Yes

FINGERPRINT READER	
Sensor vendor	Elan eFSA80ST touch sensor
Sensor type	Capacitive
DPI resolution	508 DPI
Scan area	80 x 80 pixels
False Rejection Rate	FRR (False Reject Rate) / FAR (False Acceptance Rate): FRR ~ 2% @ 1:50K FAR
False Acceptance Rate	
Mobile Voltage Operation	Mobile Voltage Operation: 2.65V to 3.6V
Operating Temperature	Operating Temperature: 32° to 95° F (0° to 35° C)
Current Consumption Image	Current Consumption Image: 50mA peak
Low Latency Wait For Finger	Low Latency Wait For Finger: <900 uA
Capture Rate	Capture Rate: 20cm/sec
ESD Resistance	ESD Resistance: IEC 61000-4-2 (+15KV)
Detection Matrix	Detection Matrix: 508 dpi / 4x4mm sensor area



ENVIRONMENTAL DATA

Eco-Label Certifications &	This product has received or is in the process of being certified to the following approvals and may				
declarations	be labeled with one or more of these marks:				
	IT ECO declaration				
	US ENERGY STAR®				
	US Federal Energy Management Program (FEMP) EPEAT Could us sistered in the United States Constants (In a second part for an electronic second seco				
	EPEAT ^{II} Gold registered in the United States. See http://www.epeat.net for registration				
	 TCO- N/A 	status in your country.			
	-	servation Program (CECP)			
		 China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) 			
	Taiwan Green Mai				
	Korea Eco-label				
		 Japan PC Green label* 			
Sustainable Impact	• 2% post-consumer recyc				
Specifications	Low halogen	•			
	-	ted cushions are 100% susta	inably sourced and recyclable		
			nably sourced and recyclable		
	 Bulk packaging available 				
System Configuration	-	•••	and Declared Noise Emissions data for the		
	Notebook model is based o	on a "Typically Configured No	otebook".		
Energy Consumption					
Energy Consumption (in accordance with US					
ENERGY STAR [®] test					
method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz		
Normal Operation (Sort					
idle)	3.29 W	2.36 W	3.14 W		
Normal Operation (Long					
idle)	2.02 W 2.12 W 1.88 W				
Sleep	0.41 W 0.43 W 0.41 W				
Off	0.36 W	0.38 W	0.36 W		
	Noto:				
	Note: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S.				
	Environmental Protection Agency (EPA) ENERGY STAR [®] specifications for computers. If a model				
	family does not offer ENERGY STAR [®] compliant configurations, then energy efficiency data listed				
	is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a				
	is for a typically configure	2	rive, a high efficiency power supply, and a		
	-	2	rive, a high efficiency power supply, and a		
Heat Dissipation*	is for a typically configure Microsoft Windows® opera	iting system.			
Heat Dissipation* Normal Operation (Short	is for a typically configure	2	rive, a high efficiency power supply, and a 100VAC, 50Hz		
	is for a typically configure Microsoft Windows® opera	iting system.			
Normal Operation (Short	is for a typically configure Microsoft Windows® opera 115VAC, 60Hz	ating system. 230VAC, 50Hz	100VAC, 50Hz		
Normal Operation (Short idle)	is for a typically configure Microsoft Windows® opera 115VAC, 60Hz	ating system. 230VAC, 50Hz	100VAC, 50Hz		
Normal Operation (Short idle) Normal Operation (Long	is for a typically configure Microsoft Windows® opera 115VAC, 60Hz 11.3 BTU/hr	ating system. 230VAC, 50Hz 8.1 BTU/hr	100VAC, 50Hz 10.7 BTU/hr		



		*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service lev attained for one hour.			
Declared Noise Emissions		Sound Power	Sound P	ressure	
(in accordance with ISO 7779 and ISO 9296)				ecibels)	
Typically Configured – Idle	3.0 16.4				
Fixed Disk – Random writes	3.0 18.0				
Optical Drive – Sequential reads					
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the				
	Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.				
Additional Information Packaging Materials	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net Plastics parts weighing over 25 grams used in the product are marked per IS011469 an IS01043. This product is 92.9% recycle-able when properly disposed of at end of life. 			al and Electronic tate of California; Safe dard at the Gold level, see marked per ISO11469 and at end of life. 256 g	
		PAPER/Molded Pulp	170 g		
	Internal:	PLASTIC/Polyethyler	13 g		
	PLASTIC/Polypropylene - PP 3 g				
	The plastic packaging material contains at least 0.0% recycled content.				
	The corrugated paper packaging materials contains at least 62.0% recycled content.				
RoHS Compliance	the restriction to our product legislation in We believe the elimination of substances— pertains to e We met our work requirement scope of the evolve.	P Inc. complies fully with materials regulations. We were among the first companies to extend ne restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive o our products worldwide through the HP GSE. HP has contributed to the development of related egislation in Europe, as well as China, India, and Vietnam. Ve believe the RoHS directive and similar laws play an important role in promoting industry-wide limination of substances of concern. We have supported the inclusion of additional ubstances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that ertains to electrical and electronics products. Ve met our voluntary objective to achieve worldwide compliance with the new EU RoHS equirements for virtually all relevant products by July 2013, and we will continue to extend the cope of the commitment to include further restricted substances as regulations continue to volve. o obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.			



Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer
	to the HP General Specification for the Environment at
	http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html
):
	Asbestos
	Certain Azo Colorants
	Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
	Cadmium
	Chlorinated Hydrocarbons
	Chlorinated Paraffins
	Bis(2-Ethylhexyl) phthalate (DEHP)
	Benzyl butyl phthalate (BBP)
	Dibutyl phthalate (DBP)
	Diisobutyl phthalate (DIBP)
	Formaldehyde
	Halogenated Diphenyl Methanes
	Lead carbonates and sulfates
	Lead and Lead compounds
	Mercuric Oxide Batteries
	 Nickel – finishes must not be used on the external surface designed to be frequently
	handled or carried by the user.
	Polybrominated Biphenyls (PBBs)
	Polybrominated Biphenyl Ethers (PBBEs) Delubraminated Biphenyl Ovides (BBBCs)
	Polybrominated Biphenyl Oxides (PBBOs)
	Polychlorinated Biphenyl (PCB)
	Polychlorinated Terphenyls (PCT)
	• Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has
	been voluntarily removed from most applications.
	Radioactive Substances
	Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	
rackaying usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in
	packaging materials.
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	Design packaging materials for ease of disassembly.
	• Maximize the use of post-consumer recycled content materials in packaging materials.
	Use readily recyclable packaging materials such as paper and corrugated materials.
	 Reduce size and weight of packages to improve transportation fuel efficiency.
	• Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management	HP offers end-of-life HP product return and recycling programs in many geographic areas. To
and Recycling	recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest
and netyting	HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible
	manner.



		The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.			
HP, Inc. Environmental	Corporate	For more information about HP's commitment to the environment:			
Information		Global Citizenship Report			
		http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications			
		http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates:			
		http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and			
		http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf			
footnotes		 Percentage of ocean-bound plastic contained in each component varies by product Recycled plastic content percentage is based on the definition set in the IEEE 1680.1- 			
		2018 standard.			
		• External power supplies, WWAN modules, power cords, cables and peripherals excluded.			
		 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers. 			
		• Fiber cushions made from 100% recycled wood fiber and organic materials.			

COUNTRY OF ORIGIN

China

Options and Accessories (sold separately and availability may vary by country)

Category	Description	Part Number
Audio/Video	HP Wired USB-A Stereo Headset	428K6AA
	HP Wired 3.5mm Stereo Headset	428K7AA
	HP 500 BT Headset	53L34AA
	HP 365 BT Speaker	567D3AA
Cases	HP Prelude Backpack 15.6	1E7D6AA
	HP Prelude Top Load 15.6	1E7D7AA
	HP Prelude Pro Recycle Backpack	1X644AA
	HP Prelude Pro Recycle Top Load	1X645AA
	HP Prelude Pro Recycle Backpack	1X644AA
	HP Prelude Pro Recycle Top Load	1X645AA
	HP Executive 14.1 Slim Topload	6KD04AA
	HP Executive 15.6 Backpack	6KD07AA
	HP Executive 15.6 Top Load	6KD06AA
	HP Renew Business 14.1" Bag	3E5F9AA
	HP Renew Business 17.3" Backpack	3E2U5AA
	HP Renew Business 14.1" Sleeve	3E2U7AA
	HP Renew Business 15.6" Bag	3E5F8AA
	HP Renew Business 17.3" Bag	3E2U6AA
	HP Renew Business 14.1" Sleeve	3E2U7AA
Hub	HP USB-C to USB-A Hub	Z6A00AA
Adapter	HP USB 3.0 to Gigabit Adapter	N7P47AA
	HP USB-C to RJ45 Adapter	V7W66AA
	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP USB-C to RJ45 Adapter G2	4Z527AA
	HP USB 3.0 to Gig RJ45 Adapter G2	4Z7Z7AA
Keyboard/Combo	HP 975 USB+BT Dual-Mode Wireless Keyboard	3Z726AA
	HP 655 Wireless Keyboard and Mouse Combo	4R009AA
	HP 225 Wired Mouse and Keyboard Combo	286J4AA
	HP 235 Wireless Mouse and Keyboard Combo	1Y4D0AA
Mouse	HP USB Premium Wireless Mouse	1JR31AA
	HP 435 Multi-Device Wireless Mouse	3B4Q5AA
	HP Creator USB-A+Bluetooth 935 Wireless Mouse Black	1DOK8AA
	HP USB-A+Bluetooth Travel Bluetooth Mouse	6SP30AA
	HP 235 Slim Wireless Mouse	4E407AA
Power	HP 65W Smart AC Adapter	Нбү89АА
Commodity	HP USB DVD-Writer EXT ODD	F2B56AA



Summary of Changes

Date of change	Version History		Description of change
March 14, 2022	V1 to V2	Added	Battery Compliance in Power section
April 14, 2022	V2 to V3	Added	Reference for USB ports and Environmental Data
April 15, 2022	V3 to V4	Added	MIL-STD test in At a Glance section
June 10, 2022	V4 to V5	Updated	TechSpecs
June 30, 2022	V5 to V6	Updated	Intel® Pentium® Silver Processor
August 5, 2022	V6 to V7	Updated	Eco-Label Certifications & declarations
August 8, 2022	V7 to V8	Updated	Memory Slots
	V8 to V9		

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